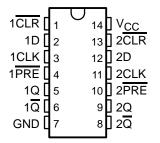
SCHS231D - SEPTEMBER 1998 - REVISED DECEMBER 2002

- AC Types Feature 1.5-V to 5.5-V Operation and Balanced Noise Immunity at 30% of the Supply
- Speed of Bipolar F, AS, and S, With Significantly Reduced Power Consumption
- Balanced Propagation Delays
- ±24-mA Output Drive Current
 Fanout to 15 F Devices
- SCR-Latchup-Resistant CMOS Process and Circuit Design
- Exceeds 2-kV ESD Protection Per MIL-STD-883, Method 3015

CD54AC74...F PACKAGE CD74AC74...E OR M PACKAGE (TOP VIEW)



description/ordering information

The 'AC74 dual positive-edge-triggered devices are D-type flip-flops.

A low level at the preset (PRE) or clear (CLR) inputs sets or resets the outputs, regardless of the levels of the other inputs. When PRE and CLR are inactive (high), data at the data (D) input meeting the setup time requirements is transferred to the outputs on the positive-going edge of the clock pulse. Clock triggering occurs at a voltage level and is not related directly to the rise time of the clock pulse. Following the hold-time interval, data at the D input can be changed without affecting the levels at the outputs.

ORDERING INFORMATION

TA	PACKAGET		ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – E	Tube	CD74AC74E	CD74AC74E
–55°C to 125°C	SOIC – M	Tube	CD74AC74M	AC74M
-55 C to 125 C	SOIC - M	Tape and reel	CD74AC74M96	AC74IVI
	CDIP – F	Tube	CD54AC74F3A	CD54AC74F3A

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE (each flip-flop)

	INP	UTS		OUTI	PUTS
PRE	CLR	CLK	D	Q	Q
L	Н	Х	Х	Н	L
Н	L	X	Χ	L	Н
L	L	X	Χ	н‡	н‡
Н	Н	\uparrow	Н	Н	L
Н	Н	\uparrow	L	L	Н
Н	Н	L	Χ	Q_0	\overline{Q}_0

[‡] This configuration is nonstable; that is, it does not persist when PRE or CLR returns to its inactive (high) level.

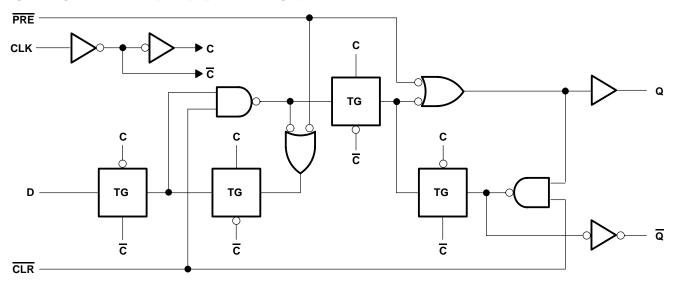


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SCHS231D – SEPTEMBER 1998 – REVISED DECEMBER 2002

logic diagram, each flip-flop (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	0.5 V to 6 V
Input clamp current, I _{IK} (V _I < 0 or V _I > V _{CC}) (see Note 1)	
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{CC}) (see Note 1)	±50 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±50 mA
Continuous current through V _{CC} or GND	±100 mA
Package thermal impedance, θ _{JA} (see Note 2): E package	80°C/W
M package	86°C/W
Storage temperature range, T _{stq}	65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
 - 2. The package thermal impedance is calculated in accordance with JESD 51-7.



recommended operating conditions (see Note 3)

			T _A = 25°C		25°C -55°C to 125°C		–40°C to 85°C		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
Vcc	Supply voltage		1.5	5.5	1.5	5.5	1.5	5.5	V
		V _{CC} = 1.5 V	1.2		1.2		1.2		
VIH	High-level input voltage	V _{CC} = 3 V	2.1		2.1		2.1		V
		V _{CC} = 5.5 V	3.85		3.85		3.85		
		V _{CC} = 1.5 V		0.3		0.3		0.3	
VIL	Low-level input voltage	V _{CC} = 3 V		0.9		0.9		0.9	V
		V _{CC} = 5.5 V		1.65		1.65		1.65	
٧ _I	Input voltage		0	VCC	0	VCC	0	VCC	V
٧o	Output voltage		0	VCC	0	VCC	0	VCC	V
loh	High-level output current	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		-24		-24		-24	mA
l _{OL}	Low-level output current	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		24		24		24	mA
Δt/Δν	Input transition rise or fall rate	$V_{CC} = 1.5 \text{ V to 3 V}$		50		50		50	ns/V
ΔυΔν	input transition rise of fall fate	V _{CC} = 3.6 V to 5.5 V		20		20		20	115/ V

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		VCC	T _A = 25°C		–55°C to 125°C		–40°C to 85°C		UNIT	
				MIN	MAX	MIN	MAX	MIN	MAX		
			1.5 V	1.4		1.4		1.4			
		I _{OH} = -50 μA	3 V	2.9		2.9		2.9			
			4.5 V	4.4		4.4		4.4			
Voн	$V_I = V_{IH}$ or V_{IL}	$I_{OH} = -4 \text{ mA}$	3 V	2.58		2.4		2.48		V	
		$I_{OH} = -24 \text{ mA}$	4.5 V	3.94		3.7		3.8			
		$I_{OH} = -50 \text{ mA}^{\dagger}$	5.5 V			3.85					
		$I_{OH} = -75 \text{ mA}^{\dagger}$	5.5 V					3.85			
			1.5 V		0.1		0.1		0.1		
		Ι _Ο L = 50 μΑ	3 V		0.1		0.1		0.1		
			4.5 V		0.1		0.1		0.1		
V_{OL}	$V_I = V_{IH}$ or V_{IL}	I _{OL} = 12 mA	3 V		0.36		0.5		0.44	V	
		I _{OL} = 24 mA	4.5 V		0.36		0.5		0.44		
		$I_{OL} = 50 \text{ mA}^{\dagger}$	5.5 V				1.65				
		I _{OL} = 75 mA [†]	5.5 V						1.65		
lį	V _I = V _{CC} or GND		5.5 V		±0.1		±1		±1	μΑ	
ICC	$V_I = V_{CC}$ or GND,	IO = 0	5.5 V		4		80		40	μΑ	
Ci					10		10		10	pF	

[†] Test one output at a time, not exceeding 1-second duration. Measurement is made by forcing indicated current and measuring voltage to minimize power dissipation. Test verifies a minimum 50-Ω transmission-line drive capability at 85°C and 75-Ω transmission-line drive capability at 125°C.



SCHS231D - SEPTEMBER 1998 - REVISED DECEMBER 2002

timing requirements over recommended operating free-air temperature range, $V_{CC} = 1.5 \text{ V}$ (unless otherwise noted)

			–55°(125		–40°C to 85°C		UNIT
			MIN MA		MIN	MAX	
fclock	Clock frequency			9		10	MHz
	Pulse duration	PRE or CLR low	50		44		ns
t _W		CLK	56		49		
+	Catus time	Data	44		39		ns
t _{su}	Setup time	PRE or CLR inactive					ns
t _h	Hold time	Data after CLK↑	0		0		ns
t _{rec}	Recovery time, before CLK↑	CLR↑ or PRE↑	34		30		ns

timing requirements over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

				–55°C to 125°C		–40°C to 85°C	
			MIN	MAX	MIN	MAX	
fclock	Clock frequency			79		90	MHz
	Pulse duration	PRE or CLR low	5.6		4.9		ns
t _W	Pulse duration	CLK	6.3		5.5		115
	Cabinations	Data	4.9		4.3		ns
t _{su}	Setup time	PRE or CLR inactive					ns
th	Hold time	Data after CLK↑	0		0		ns
t _{rec}	Recovery time, before CLK↑	CLR↑ or PRE↑	4.7		4.1		ns

timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

			–55° 125		–40°C to 85°C		UNIT
			MIN MA		MIN	MAX	
fclock	Clock frequency			110		125	MHz
	Pulse duration	PRE or CLR low	4		3.5		ns
t _W		CLK	4.5		3.9		
+	Cotup time	Data	3.5		3.1		ns
t _{su}	Setup time	PRE or CLR inactive					ns
t _h	Hold time	Data after CLK↑	0		0		ns
t _{rec}	Recovery time, before CLK↑	CLR↑ or PRE↑	2.7	·	2.4		ns

SCHS231D - SEPTEMBER 1998 - REVISED DECEMBER 2002

switching characteristics over recommended operating free-air temperature range, V_{CC} = 1.5 V, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	-55°C to 125°C		TO 1			UNIT
	(1141 01)	(0011 01)	MIN	MAX	MIN	MAX		
f _{max}			9		10		MHz	
tPLH	01.14	Q or $\overline{\mathbb{Q}}$		125		114	20	
t _{PHL}	CLK			125		114	ns	
t _{PLH}	PRE or CLR	Q or $\overline{\mathbb{Q}}$		132		120	no	
^t PHL	PRE OF CLR	QorQ		144		131	ns	

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	FROM TO (INPUT) (OUTPUT)		C to ∘C	–40°0 85°		UNIT
	(1141 01)	(0011 01)	MIN	MAX	MIN) 6 12.7	
f _{max}			79		90		MHz
t _{PLH}	CLK	Q or $\overline{\mathbb{Q}}$	3.5	14	3.6	12.7	nc
t _{PHL}	CLK		3.5	14	3.6	12.7	ns
tPLH	PRE or CLR	Q or $\overline{\mathbb{Q}}$	3.7	14.7	3.8	13.4	ns
^t PHL	FRE UI CER		4	16.1	4.1	14.6	115

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

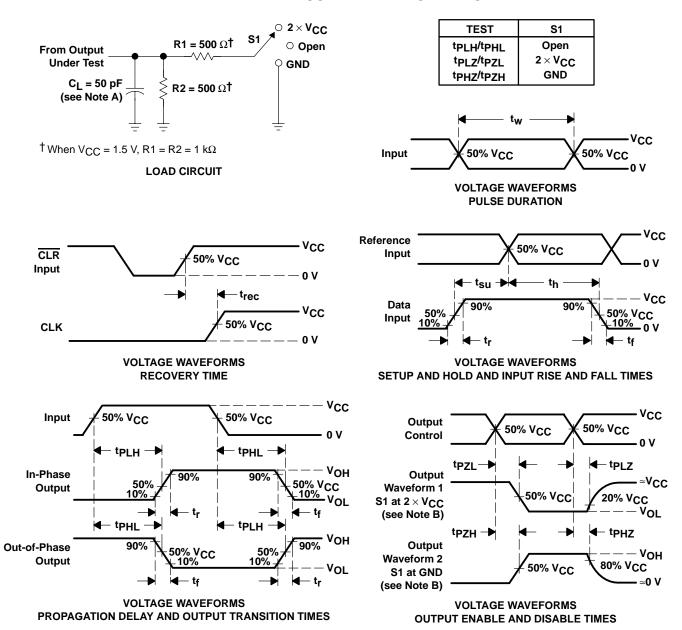
PARAMETER	FROM (INPUT)	TO (OUTPUT)	–55°C to 125°C				UNIT
	(1141 31)	(0011 01)	MIN	MAX	MIN	MAX	
f _{max}			110		125		MHz
tPLH	01.14	Q or $\overline{\mathbb{Q}}$	2.5	10	2.6	9.1	
t _{PHL}	CLK		2.5	10	2.6	9.1	ns
tPLH	PRE or CLR	Q or Q	2.6	10.5	2.7	9.5	ns
^t PHL	FRE OI CER	Q 61 Q	2.9	11.5	3	10.4	115

operating characteristics, T_A = 25°C

		PARAMETER	TYP	UNIT
I	C _{pd}	Power dissipation capacitance	55	pF



PARAMETER MEASUREMENT INFORMATION



- NOTES: A. C_L includes probe and test-fixture capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_Ω = 50 Ω, t_f = 3 ns, t_f = 3 ns. Phase relationships between waveforms are arbitrary.
 - D. For clock inputs, f_{max} is measured with the input duty cycle at 50%.
 - E. The outputs are measured one at a time with one input transition per measurement.
 - F. tpLH and tpHL are the same as tpd.
 - G. tpz and tpzH are the same as ten.
 - H. tpLz and tpHz are the same as tdis.

Figure 1. Load Circuit and Voltage Waveforms



14 LEADS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AB.



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